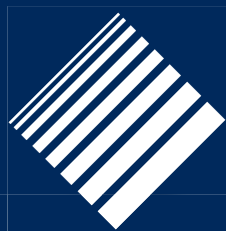


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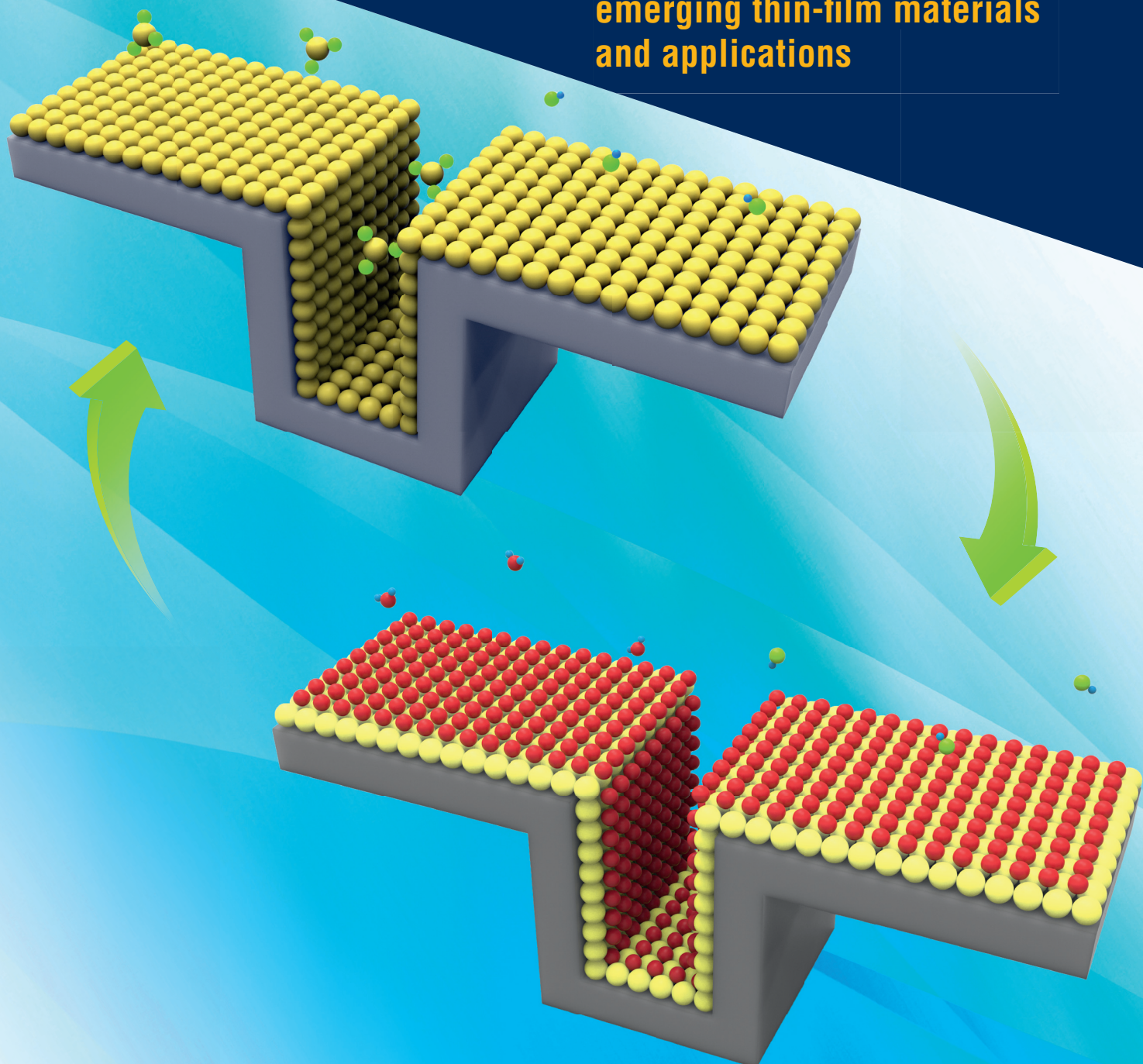
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**FOCUS ISSUE**

**Atomic layer deposition for  
emerging thin-film materials  
and applications**



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